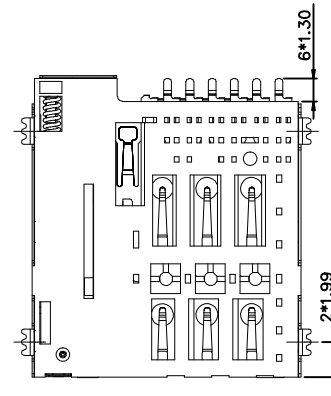
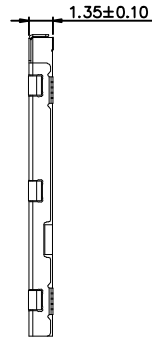
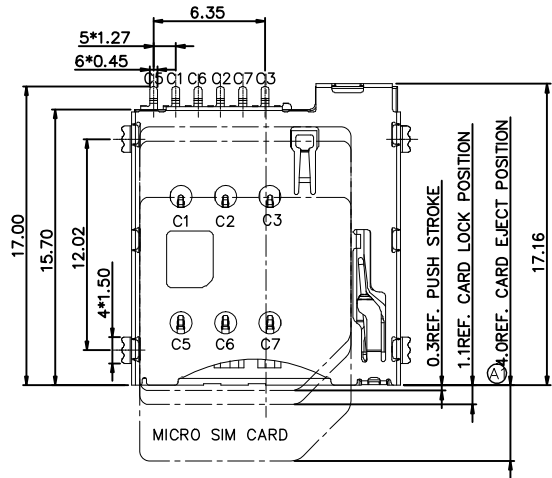
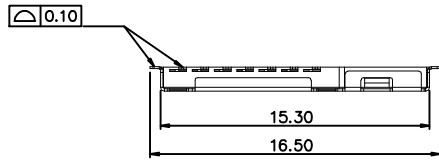


REV	DATE	ECN NO.	MODIFICATION	APPROVER
A	2016/10/14		NEW	Jason_Lee
A1	2017/05/15	RD00317051501	SIZE CHANGE	Jason_Lee



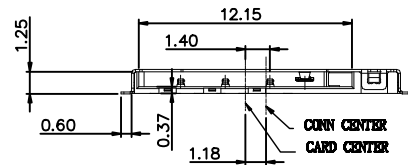
NOTES:

MATERIAL:

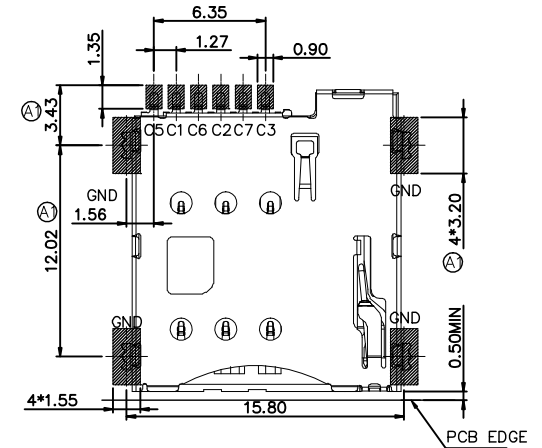
Housing: High Temperature thermoplastic,UL94V-0  
Terminal: Copper Alloy  
Shell: Stainless

SPECIALITY:

Rated Current:0.5A MAX  
Rated Voltage:50V  
Ambient Temperature Range:-40°C~+85°C  
Ambient Humidity Range :95% R.H. Max.  
Contact Resistance:100mΩ Max  
Insulation Resistance:1000MΩ/250V DC  
Dielectric Withstanding Voltage:500V AC  
Durability:5000 cycles  
Temperature 260±5°C,



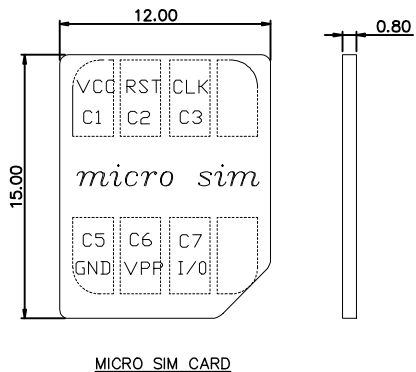
IM pin Assignment	
IN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



■ SMT SOLDER AREA  
THERE SHOULD NOT BE ANY CIRCUITRIES  
IN THE LAYOUT SPACE OF THE PRODUCTS

RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE±0.05



GENERAL TOLERANCE				UNITS mm	NAME: MICRO SIM CARD 6P PUSH PUSH	PART NO: SI63C-01200	TITLE: MICRO SIM CARD 6P PUSH PUSH SMT H=1.35mm 不带检测脚 无柱
SELECT	TOL	1	2				
X.XXX	±0.10	±0.05	±0.15		FINISH	CHKD:	SCALE SHEET REV
X.XX	±0.15	±0.13	±0.25		Q'TY	DR: JACK	1:1 1/1 A1
X.X	±0.20	±0.25	±0.5				
X.	±0.30	±0.38	±1.00				
ANGLE	±2'						

**ATOM** 深圳市爱特姆科技有限公司  
SHENZHEN ATOM TECHNOLOGY CO., LTD.